WHAT IS CLAIMED IS:

1. A polishing tool for polishing a wafer, comprising:

a base; and

a polishing layer fixed to the base,

wherein the polishing layer includes

a base material;

abrasive grains; and

an electrically conductive material,

the abrasive grains and the electrically conductive material contained in the base material, and

wherein the electrically conductive material is dispersed throughout the polishing layer to eliminate static electricity generated when the polishing layer comes into contact with the wafer, and

wherein

a portion of the electrically conductive material is exposed on an upper surface of the base material;

another portion of the electrically conductive material is exposed on a lower surface of the base material; and

the electrically conductive material exposed on the upper surface and the electrically conductive material exposed on the lower surface are connected together via electrically conductive material embedded inside the base material.

2. The polishing tool according to claim 1,

wherein the electrically conductive material comprises carbon fibers, and

the carbon fibers are included at a content of 3 wt% or more but 15 wt% or less.

3. The polishing tool according to any one of claim 1 or claim 2,

wherein the polishing layer is divided into a plurality of parts, forming a plurality of polishing layers arrayed at substantially equal intervals along a peripheral direction of the base.

4. The polishing tool according to claim 2,

wherein

the base material is made of felt, and the felt with the abrasive grains and the carbon fibers dispersed therein is obtained by:

impregnating the felt with liquid, in which the abrasive grains and the carbon fibers are mixed, or

blending the abrasive grains and the carbon fibers

in a raw material for the felt in a manufacturing process of the felt.